

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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OPB820, OPB821Z, OPB821S_Z



Features:

- Non-contact switching
- Four standard aperture sizes for high resolution
- Low profile
- 0.080" (2.03 mm) wide, 0.250" (8.89 mm) deep slot
- Choice of PCBoard or wire mountings



Description:

Each OPB820 and OPB821Z device consists of an infrared emitting diode (LED, 890 nm center wavelength) and a NPN silicon phototransistor mounted in a low-cost black plastic housing on opposite sides of an 0.080" (2.03 mm) wide slot. Each device in this series has a 0.040" (1.02 mm) wide aperture located in front of the infrared diode. Phototransistor switching occurs when an opaque object passes through the slot.

Devices are offered with 0.275" (6.96 mm) lead spacing for PCBoard mounting (OPB820) or 24" (609 mm) 26 AWG wire leads (OPB821Z).

Applications:

- Non-contact object sensing
- Assembly line automation
- Machine automation
- Equipment safety
- Machine safety

Ordering Information					
Part Number	LED Peak Wavelength	Sensor	Slot Width / Depth	Aperture Emitter/Sensor	Lead Length / Spacing
OPB820		890 nm Transistor		0.04"/ 0.04"	
OPB820S10			or 0.080" / 0.255"	0.04"/ 0.01"	0.425" / 0.275" 24"/26 AWG Wire
OPB820S5	000 555			0.04"/ 0.005"	
OPB820S3				0.04"/ 0.003"	
OPB821Z	090 11111			0.040"/ 0.040"	
OPB821S10Z				0.040"/ 0.010"	
OPB821S5Z				0.040"/ 0.005"	
OPB821S3Z				0.040"/ 0.003"	





Electrical Specifications

Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Storage and Operating Temperature	-40°C to +85°C
Lead Soldering Temperature (1/16 inch [1.6 mm] from case for 5 seconds with soldering iron) (1)	260°C
Input Diode	
Continuous Forward Current	50 mA
Peak Forward Current (1μs pulse width, 300 pps)	1 A
Reverse Voltage	2 V
Power Dissipation ⁽²⁾	100 mW
Output Phototransistor	
Collector-Emitter Voltage	30 V
Emitter-Collector Voltage	5 V

Notes:

Power Dissipation (2)

- (1) RMA flux is recommended. Duration can be extended to 10 seconds maximum when flow soldering.
- (2) For OPB820, derate linearly 1.67 mW/° C above 25° C. For OPB821Z, derate linearly 1.82 mW/° C above 25° C.
- (3) Methanol or isopropanol are recommended as cleaning agents. Plastic housing is soluble in chlorinated hydrocarbons and ketones.

Electrical Characteristics (T_A = 25°C unless otherwise noted)

SYMBOL	PARAMETER	MIN	TYP	MAX	UNITS	TEST CONDITIONS
Input Diode (Input Diode (See OP245 for additional information)					
V _F	Forward Voltage	-	-	1.7	V	I _F = 20 mA
I _R	Reverse Current	-	-	100	μΑ	V _R = 2 V
Output Phototransistor (See OP555 for additional information)						
V _{(BR)CEO}	Collector-Emitter Breakdown Voltage	30	-	-	V	I _C = 100 mA
V _{(BR)ECO}	Emitter-Collector Breakdown Voltage	5	-	-	V	Ι _Ε = 100 μΑ
I _{CEO}	Collector-Emitter Dark Current	-	-	100	nA	V _{CE} = 10 V, I _F = 0, I _E = 0
Coupled	Coupled					
V _{CE(SAT)}	Collector-Emitter Saturation Voltage OPB820, OPB821Z OPB820S3, OPB821S3Z OPB820S5, OPB821S5Z OPB820S10, OPB821S10Z	- - -	- - -	0.4 0.4 0.4 0.4	V V V	$I_{C} = 250 \; \mu\text{A, } I_{F} = 20 \; \text{mA}$ $I_{C} = 40 \; \mu\text{A, } I_{F} = 20 \; \text{mA}$ $I_{C} = 150 \; \mu\text{A, } I_{F} = 20 \; \text{mA}$ $I_{C} = 250 \; \mu\text{A, } I_{F} = 20 \; \text{mA}$
I _{C(ON)}	On-State Collector Current OPB820, OPB821Z OPB820S3, OPB821S3Z OPB820S5, OPB821S5Z OPB820S10, OPB821S10Z	500 60 300 400	- - -	- - -	μΑ μΑ μΑ μΑ	$V_{CE} = 5 \text{ V}, I_F = 20 \text{ mA}$ $V_{CE} = 5 \text{ V}, I_F = 20 \text{ mA}$ $V_{CE} = 5 \text{ V}, I_F = 20 \text{ mA}$ $V_{CE} = 5 \text{ V}, I_F = 20 \text{ mA}$

General Note

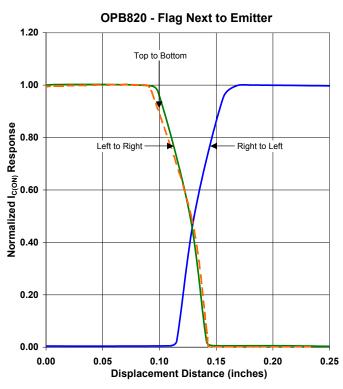
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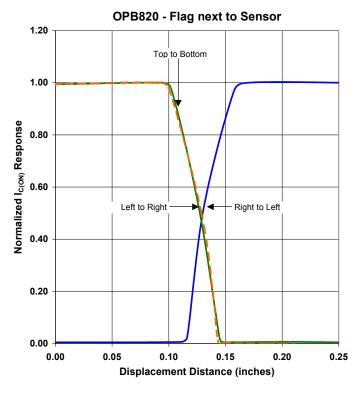
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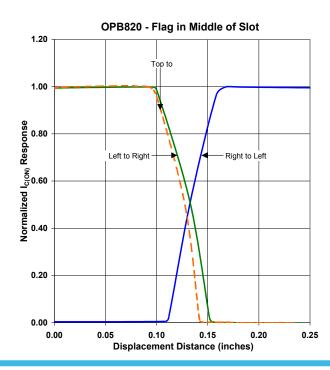
100 mW

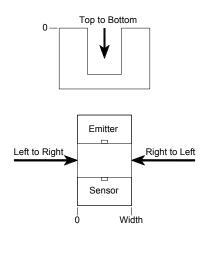
OPB820, OPB821Z, OPB821S_Z





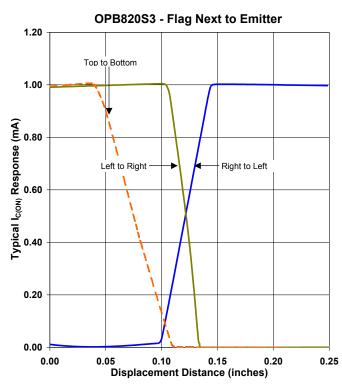


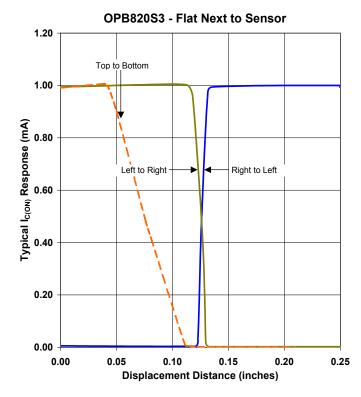


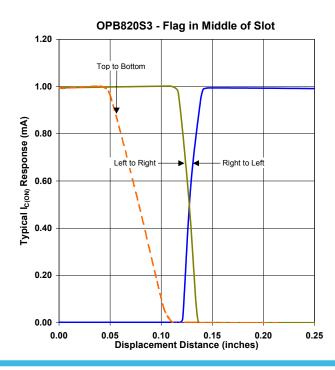


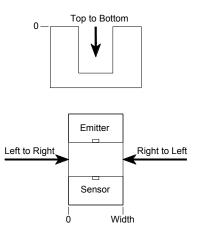
OPB820, OPB821Z, OPB821S_Z





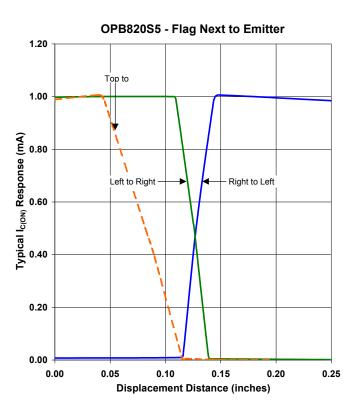


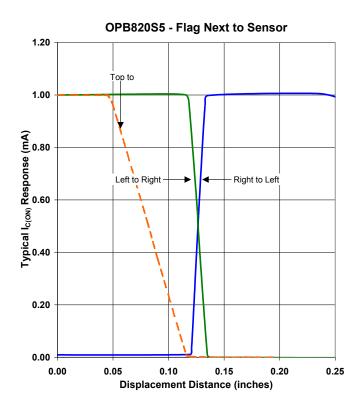


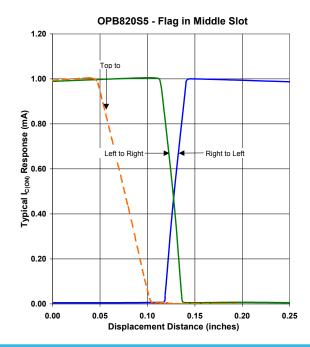


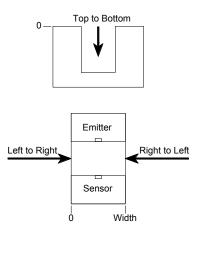
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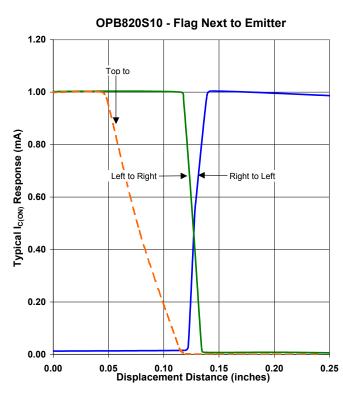


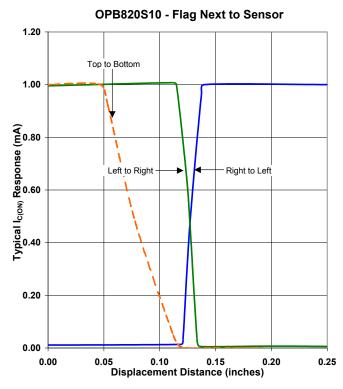


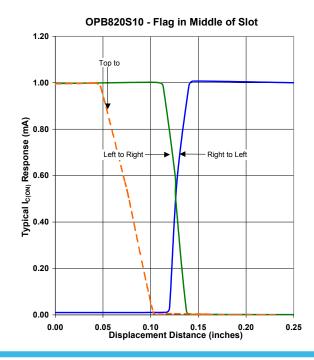


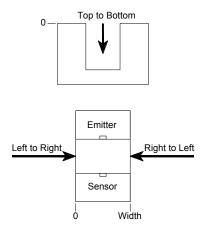
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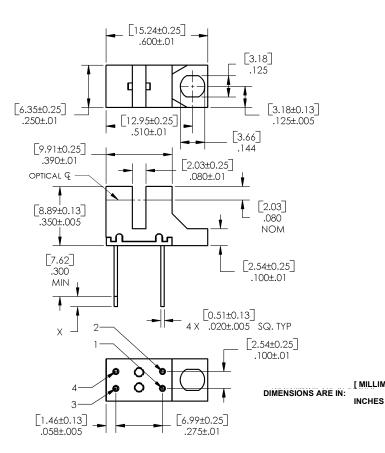


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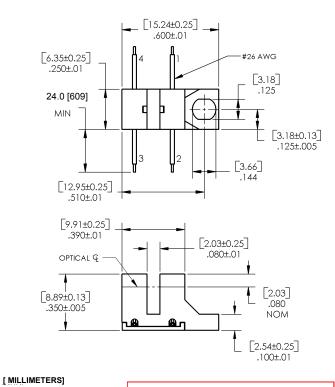


Packaging

Package Drawing OPB820



Package Drawing OPB821



CONTAINS POLYSULFONE

To avoid stress cracking, we suggest using ND Industries' Vibra-Tite for thread-locking. Vibra-Tite evaporates fast without causing structural failure in OPTEK's molded plastics.

Pin#	Description	Pin#	Description
4	Cathode	2	Collector
3	Anode	1	Emitter

Color/Pin #	Description	Color/Pin #	Description
Green-3	Cathode	White-2	Collector
Orange-4	Anode	Blue-1	Emitter

